



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2014-07-31
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	LAURENT TOSI	Representative Title	MMS MD CHAMPION
Representative Phone *	33 442 685 795	Representative Email *	laurent.tosi@st.com
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/online_tech_support.html		

Uncertainty Statement

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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STM32F205RCT6	P55W*411XXX2	A	9998	2015-06-04
Amount	UoM	Unit type	ST ECOPACK Grade	
307,98	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used or other bulk termination : add in comments	Tin (Sn), matte	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
QFP	10x10x1.4	64	L bend	
Comment	L QFP 64 10x10x1.4			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	true
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-16th June 2014				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	P55W*411XXX2					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or Dies	Other inorganic materials	11,360	mg	supplier	die	Silicon (Si)	7440-21-3		9,945	mg	875440	32291
Die or Dies				supplier	metallization	Aluminium (Al)	7429-90-5		0,024	mg	2113	78
Die or Dies				supplier	metallization	Copper (Cu)	7440-50-8		0,211	mg	18574	685
Die or Dies				supplier	metallization	Tantalum (Ta)	7440-25-7		0,984	mg	86620	3195
Die or Dies				supplier	metallization	Cobalt (Co)	7440-48-4		0,001	mg	88	3
Die or Dies				supplier	metallization	Titanium (Ti)	7440-32-6		0,002	mg	176	6
Die or Dies				supplier	metallization	Tungsten (W)	7440-33-7		0,002	mg	176	6
Die or Dies				supplier	passivation	Silicon Nitride (SiN)	68034-42-4		0,054	mg	4754	175
Die or Dies				supplier	passivation	Silicon Oxide (SiO2)	7631-86-9		0,137	mg	12060	445
LEADFRAME (MHT- C194)	Other inorganic materials	47,409	mg	supplier	ALLOY	Copper (Cu)	7440-50-8		46,200	mg	974503	150011
LEADFRAME (MHT- C194)				supplier	ALLOY	Iron (Fe)	7439-89-6		1,138	mg	24002	3695
LEADFRAME (MHT- C194)				supplier	ALLOY	Zinc (Zn)	7440-66-6		0,057	mg	1198	184
LEADFRAME (MHT- C194)				supplier	ALLOY	Phosphorus (P)	7723-14-0		0,014	mg	297	46
LEADFRAME (MHT- Ag)	Other inorganic materials	1,103	mg	supplier	COATING	Silver(Ag)	7440-22-4		1,103	mg	1000000	3580
DIE ATTACH (Evertech -AP4200)	Other inorganic materials	0,009	mg	supplier	GLUE	Epoxy	9003-36-5		0,002	mg	222222	6
DIE ATTACH (Evertech -AP4200)				supplier	GLUE	Silver(Ag)	7440-22-4		0,007	mg	777778	23
BONDING WIRE (MKE - Au wire)	Other inorganic materials	1,085	mg	supplier	BONDING WIRE	Gold (Au)	7440-57-5		1,084	mg	999078	3520
BONDING WIRE (MKE - Au wire)				supplier	BONDING WIRE	Palladium (Pd)	7440-41-7		0,001	mg	922	3
ENCAPSULATION (Sumitomo -G631HC)	Other inorganic materials	243,523	mg	supplier	MOLDING COMPOUND	Epoxy Resin	Trade secret		25,384	mg	104237	82421
ENCAPSULATION (Sumitomo -G631HC)				supplier	MOLDING COMPOUND	Silica fused (SiO3)	60676-86-0		202,909	mg	833223	658837
ENCAPSULATION (Sumitomo -G631HC)				supplier	MOLDING COMPOUND	Phenol Resin	Trade secret		13,961	mg	57329	45331
ENCAPSULATION (Sumitomo -G631HC)				supplier	MOLDING COMPOUND	Carbon Black	1333-86-4		1,269	mg	5211	4120
FINISHING - (ST380 -Sn)	Other inorganic materials	3,492	mg	supplier	EXTERNAL PLATING	Tin (Sn)	7440-31-5		3,492	mg	1000000	11338